WHAT IS CLAIMED IS:

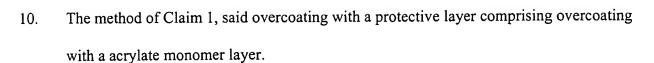
- 1. A method of fabricating a micromechanical structure, the method comprising:

 fabricating at least two micromechanical structures on a substrate;

 overcoating said micromechanical structures with a protective layer;

 overcoating said protective layer with a brittle layer; and

 sawing said brittle layer and said protective layer.
- 2. The method of Claim 1, said fabricating comprising fabricating at least two micromechanical devices on a semiconductor substrate.
- 3. The method of Claim 1, said fabricating comprising fabricating at least two micromirror devices on said substrate.
- 4. The method of Claim 1, said fabricating comprising fabricating at least two micromirror devices on a semiconductor substrate.
- 5. The method of Claim 1, said fabricating comprising fabricating at least two micromirror arrays on said substrate.
- 6. The method of Claim 1, said fabricating comprising fabricating at least two micromirror arrays on a semiconductor substrate.
- 7. The method of Claim 1, said overcoating with a protective layer comprising overcoating with a plastic layer.
- 8. The method of Claim 1, said overcoating with a protective layer comprising overcoating with a polymer resin.
- 9. The method of Claim 1, said overcoating with a protective layer comprising overcoating with a PARYLENE layer.



- 11. The method of Claim 1, said overcoating with a protective layer comprising overcoating with a acrylate oligomer layer.
- 12. The method of Claim 1, said overcoating with a protective layer comprising applying a protective overcoat by vapor deposition.
- 13. The method of Claim 1, said overcoating with a protective layer comprising applying a protective overcoat by immersing said substrate in a liquid protective overcoat material.
- 14. The method of Claim 1, said overcoating with a protective layer comprising applying a protective overcoat by spinning-on a protective overcoat layer.
- 15. The method of Claim 1, comprising:

thermally curing said protective layer.

16. The method of Claim 1, comprising:

curing said protective layer using ultraviolet light.

- 17. The method of Claim 1, said overcoating with a brittle layer comprising overcoating with a photoresist layer.
- 18. The method of Claim 1, said overcoating with a brittle layer comprising overcoating with a photoresist layer, further comprising:

baking said photoresist layer.

19. The method of Claim 1, said overcoating with a brittle layer comprising overcoating with a photoresist layer, further comprising:

deep UV hardening said photoresist layer.



- 20. The method of Claim 1, said overcoating with a brittle layer comprising overcoating with a brittle layer to prevent said protective layer from delaminating from said substrate.
- 21. The method of Claim 1, said sawing comprising sawing through said protective and overcoat layers.
- 22. The method of Claim 1, said sawing comprising sawing through said protective and overcoat layers and said substrate to separate said micromechanical devices.
- 23. The method of Claim 1, said sawing comprising sawing through said protective and overcoat layers and partially through said substrate layer.